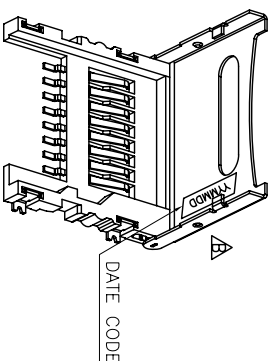
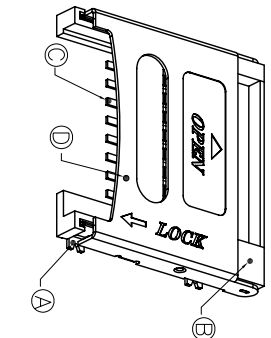


SHELL LOCK



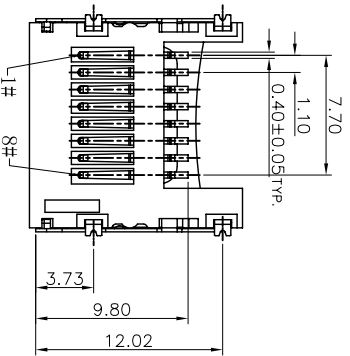
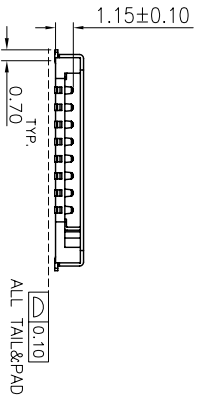
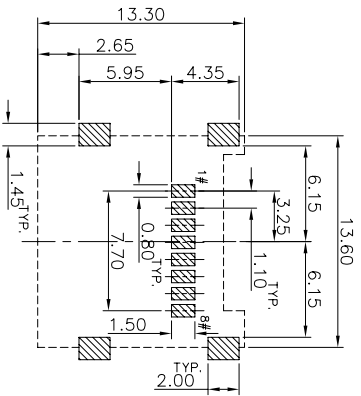
REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
A		PRELIMINARY	孫一中	10/08/07
B	△	ECR要求板底產線D/C方式 ECN NO.:C070309	孫一中	01/16/08
C		新增加膠袋封加膠膠帶 ECN NO.:C080051	孫一中	2008.05.02

SPECIFICATIONS:

- MATERIAL :  
HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0-BLACK  
SHELL:STAINLESS STEEL.  
CONTACT:COPPER ALLOY.  
DETECT PIN: COPPER ALLOY.
- PLATING:  
CONTACT: 1u" Min. Au PLATING IN CONTACT AREA;  
100u" Min. Sn PLATED OVERALL,  
50u" Min. Ni UNDERPLATED OVERALL.  
PAD:100u" Min. Sn PLATING OVER ALL  
50u" Min. Ni UNDERPLATED OVERALL .
- ELECTRICAL CHARACTERISTIC:  
CONNECT RESISTANCE:80 MILLIONMS/PIN Max.  
INSULATION RESISTANCE:1000 MEGAOHMS Min.  
VOLTAGE WITHSTAND:500V AC for 1minute  
4. TO CONFORM TO THE SINGATRON HSF SPEC.
- DATE CODE: YMMDD  

Year	Month	Day
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RECOMMENDED PCB PATTERN LAYOUT  
TOLERANCE: ±0.05



Pin No.	Name	Type	DESCRIPTION
1	DAT2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

D	Shell	1	STAINLESS STEEL.	/
C	Contact	8	COPPER ALLOY	SEE TABLE
B	Housing	1	HIGH TEMP. THERMOPLASTIC	(UL94-V0) BLACK
A	Sold Pin	4	COPPER ALLOY	Sn:100u"min Ni:50u"min

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X :±0.5 X :±2°  
X.X :±0.3 X.X :±1°  
X.XX :±0.2

TITLE TRANS FLASH HIGNE

DWN 孫一中 PART NO. ZCA3000-000111  
CHKD SCALE 3:1 UNIT: mm  
APVD MUYUAN SIZE: A3 SHEET: 10F1 REV: C

Singatron Enterprise Co., Ltd.  
信音企業股份有限公司

CUSTOMER COPY

A B C D E F

1 2 3 4 5 6 7 8